

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Hiroyuki YASUDA	04/30/2009
<b>RECEIVING PARTY DATA</b>	
Name:	SUMITOMO BAKELITE CO., LTD.
Street Address:	5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku
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<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	12526265
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ATTORNEY DOCKET NUMBER:	01159_1033
NAME OF SUBMITTER:	Masayasu Mori
Total Attachments: 2 source=01159_1033_Assignment#page1.tif source=01159_1033_Assignment#page2.tif	

OP \$40.00 12526265

Attorney Docket No.:

Client Docket No.:

## ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I(We) the undersigned, Hiroyuki YASUDA, hereby sell, assign, and transfer to SUMITOMO BAKELITE CO., LTD., a corporation of Japan, having a principal place of business at 5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku, Tokyo 1400002 Japan ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent, entitled:

ADHESIVE FILM FOR SEMICONDUCTOR AND SEMICONDUCTOR DEVICE USING THE ADHESIVE FILM

- which has been executed by the undersigned concurrently herewith,  
 which was filed on \_\_\_\_\_ and assigned Serial No. \_\_\_\_\_

and in to said application and all divisional, continuing, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all assignments and powers of attorney; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

**Each Inventor: Please Sign and Date Below:**

April 30, 2009  
Date

Hiroyuki Yasuda  
Name: Hiroyuki YASUDA